

SOT1169-1

plastic low profile fine-pitch ball grid array package; 256 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFPGA256
Package type industry code	LFPGA256
Package style descriptive code	LFPGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	1-3-2010

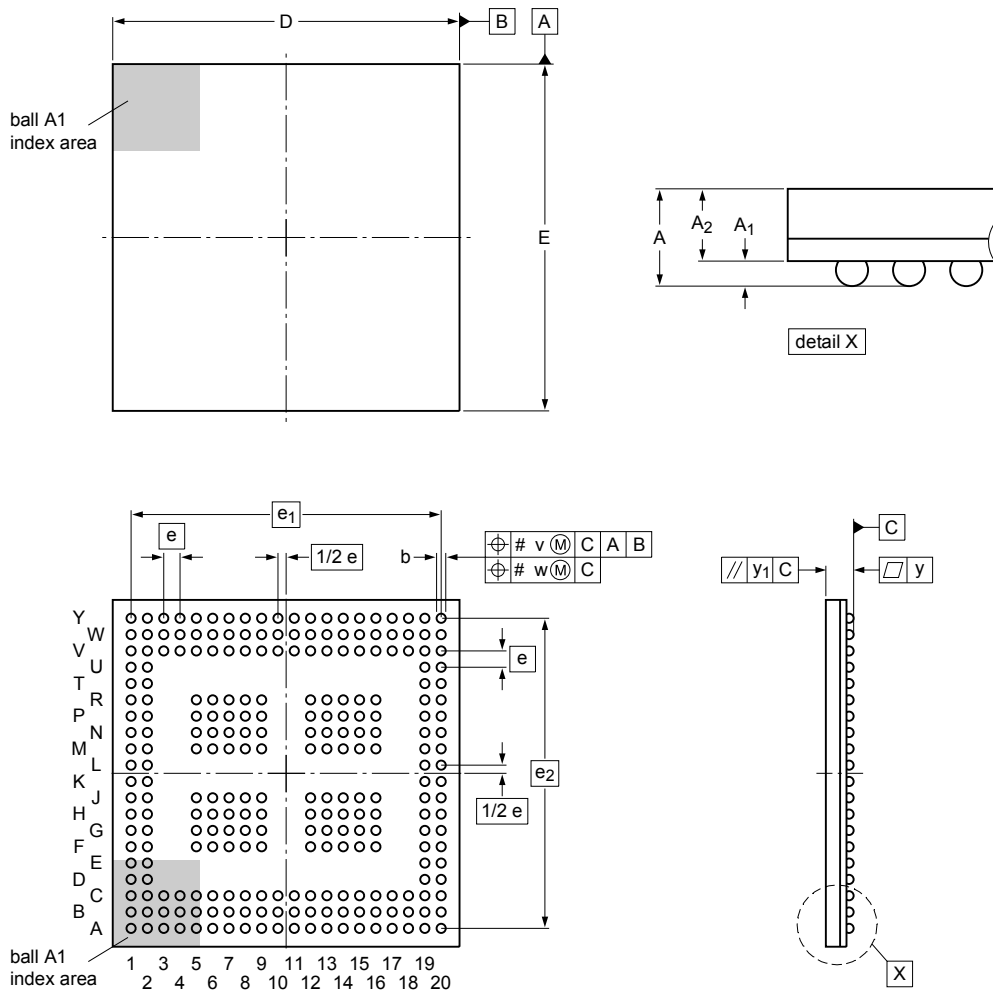
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	16.9	-	17	17.1	mm
E	package width	16.9	-	17	17.1	mm
A	seated height	1.25	-	1.36	1.5	mm
A ₂	package height	0.95	-	1.01	1.1	mm
e	nominal pitch	-	-	0.8	-	mm
n ₂	actual quantity of termination	-	-	256	-	



2. Package outline

LFBGA256: plastic low profile fine-pitch ball grid array package; 256 balls SOT1169-1



Dimensions

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
max	1.50	0.40	1.10	0.50	17.1	17.1							
mm nom	1.36	0.35	1.01	0.45	17.0	17.0	0.8	15.2	15.2	0.15	0.08	0.12	0.10
min	1.25	0.30	0.95	0.40	16.9	16.9							

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1169-1	---	---	---		10-02-05- 10-03-01

Fig. 1. Package outline LFBGA256 (SOT1169-1)

3. Legal information

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